

Semiconductor production at Bosch

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- ▶ **Current portfolio**

Bosch manufactures electronic components for vehicles and for consumer electronics. These include **microelectromechanical systems (MEMS)** such as acceleration, pressure, yaw-rate, environmental, mass-flow, and magnetic field sensors, **application-specific integrated circuits (ASICs)**, and **power semiconductors**.
- ▶ **Manufacturing sites**

Reutlingen (150-mm and 200-mm technology)
Dresden (300-mm technology)
- ▶ **Patents**

Bosch holds more than 1,500 patents and patent applications in the field of semiconductor technology, 1,000 of which are for MEMS technology.
- ▶ **Market**

Bosch manufactures MEMS sensors, integrated circuits, and power semiconductors for in-house requirements. A large portion of the portfolio is also offered in the open market.
- ▶ **History**

The company has been developing and manufacturing microelectronic components and systems since the 1950s. Semiconductors (integrated circuits) have been manufactured at the wafer fab in Reutlingen since 1970. Bosch developed the microfabrication technique for microelectromechanical sensors (MEMS sensors) nearly 25 years ago, and is now the world market leader in this field.

► Capital expenditure

In its wafer fabs in Reutlingen and Dresden alone, Bosch has invested more than 2.5 billion euros since 200-millimeter technology was introduced in 2010. On top of this, billions of euros have been invested in developing microelectronics.